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# Electronics Packaging 2

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*ECS Transactions, Volume 3, Issue 16*  
Electronics Packaging 2

**Table of Contents**

Preface

Development and Characterization of Plating Cell Geometry for PCB and  
Packaging Applications. 1

*H. Garich, L. Gebhart, E. Taylor, M. Inman and H. McCrabb*

Electrochemical Micromachining of Patterned Aluminum Films by Porous-type  
Anodization 11

*D. A. Brevnov*

Author Index 19